

## C1206X189BATACTU

Aliases (C1206X189BATAC7800)

SMD Comm X8G HT150C Flex, Ceramic, 1.8 pF, +/-0.1 pF, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	15 mg
Shelf Life	78 Weeks
MSL	1

1.8 pF

100 GOhms

Dimensions	
Chip Size	1206
L	3.3mm +/-0.4mm
W	1.6mm +/-0.35mm
Т	0.78mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm

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S	1.5mm MIN
В	0.6mm +/-0.25mm
Packaging Specifications	

L	3.3mm +/-0.4mm	Measurement Condition	1 MHz 1.0 Vrms
W	1.6mm +/-0.35mm	Tolerance	+/-0.1 pF
Т	0.78mm +/-0.20mm	Voltage DC	250 VDC
S	1.5mm MIN	Dielectric Withstanding Voltage	625 VDC
В	0.6mm +/-0.25mm	Temperature Range	-55/+150°C
		Temp. Coefficient	X8G
Packaging Specifications		Capacitance Change with	30 ppm/C, 1MegaHz 1.0Vrms
Packaging	T&R, 180mm, Plastic Tape	Reference to +25°C and 0 VDC Applied (TCC)	., , , ,
Packaging Quantity	4000	Dissipation Factor	0.1% 1 MHz 1.0Vrms
		Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours

Insulation Resistance

**Specifications** Capacitance

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